

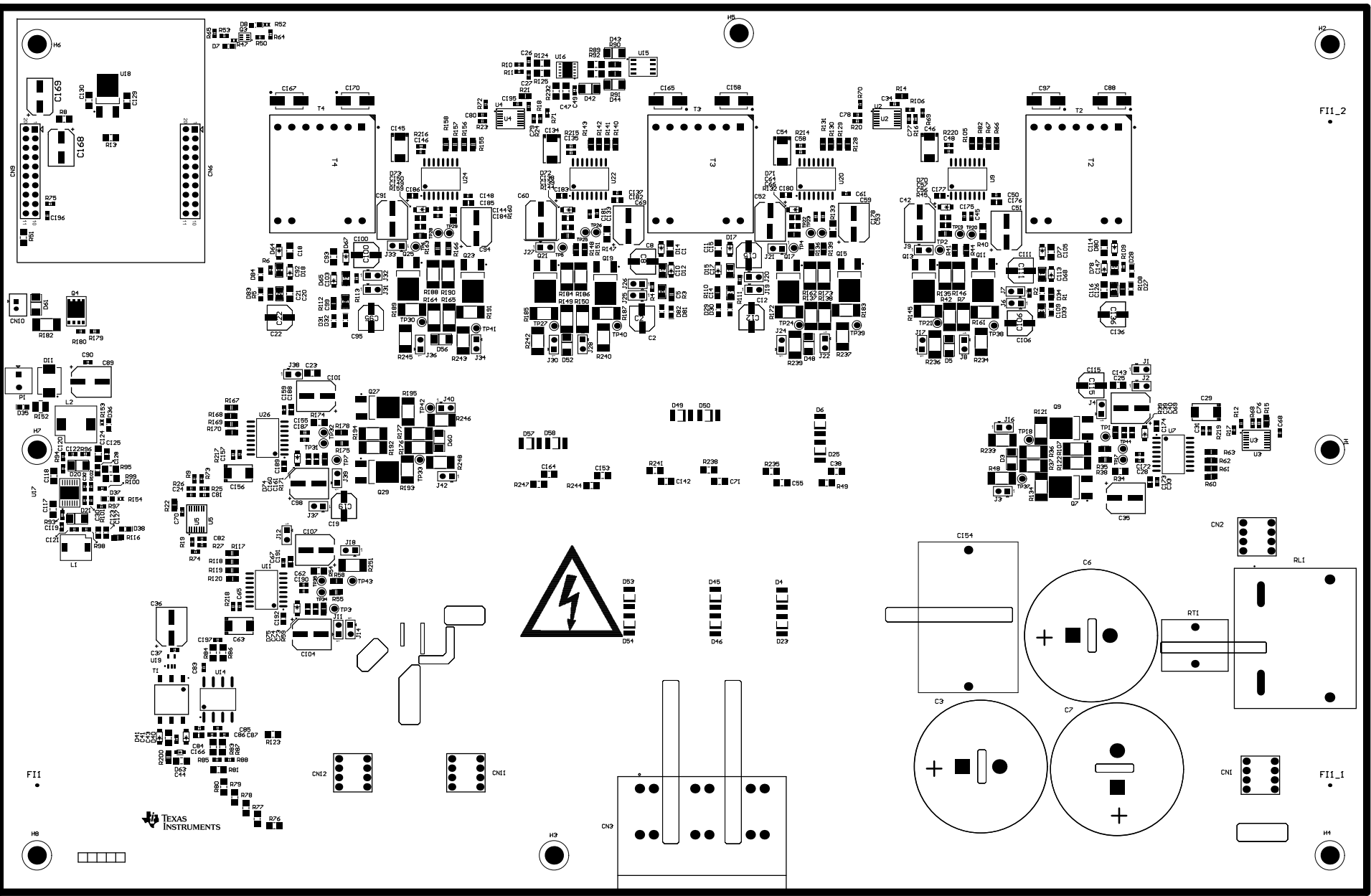
F11\_2

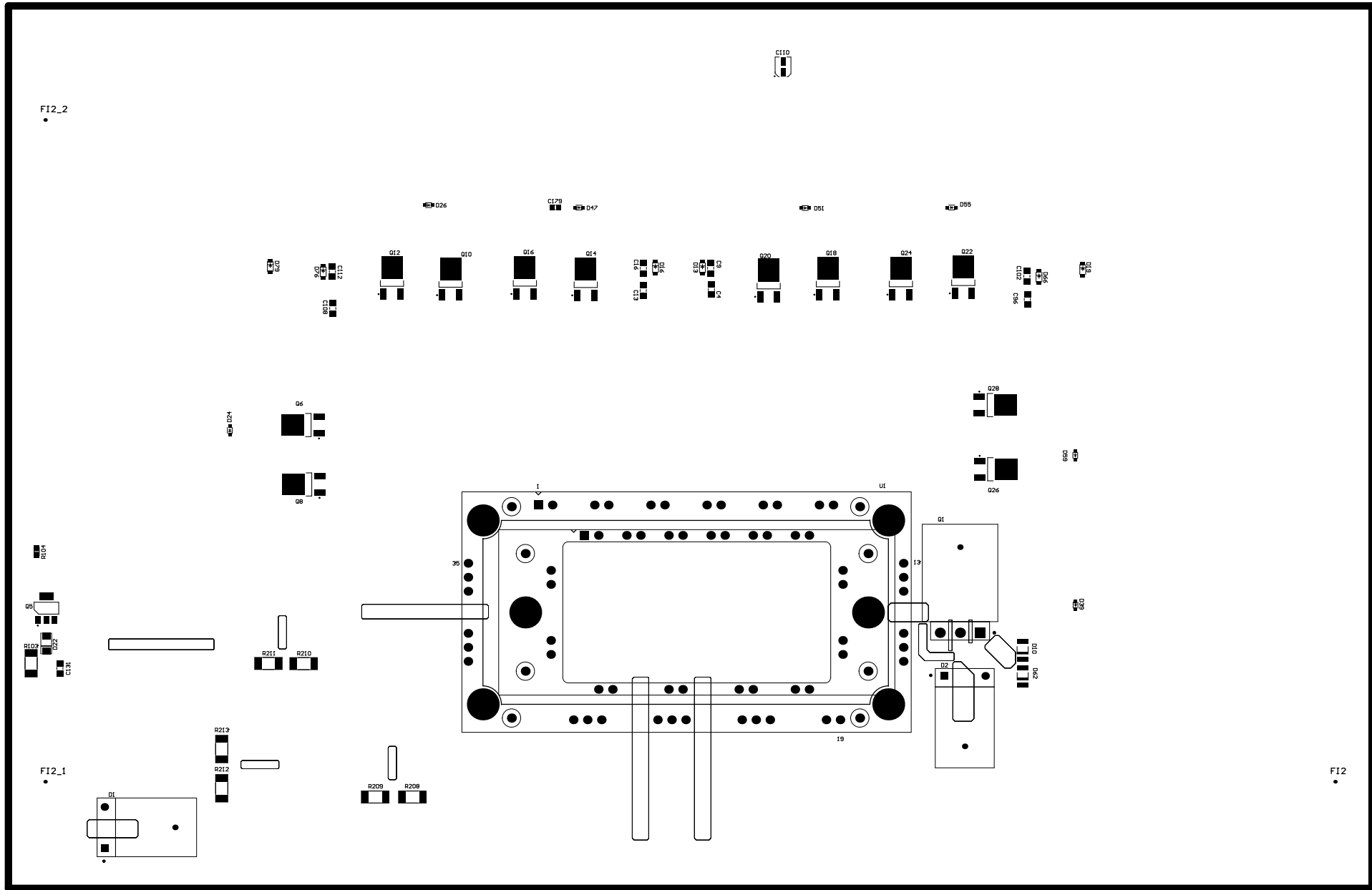
F11\_1



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: [No Variations]

|                                  |                                 |                   |                                |
|----------------------------------|---------------------------------|-------------------|--------------------------------|
| PCB VIEWED FROM TOP SIDE         | BOARD #: TIDA-00195             | REV: E1           | SUN REV: Not In VersionControl |
| LAYER NAME = ASSEMBLY TOP        |                                 |                   |                                |
| PLOT NAME = Top Assembly Drawing | GENERATED : 23-03-2015 18:03:36 | TEXAS INSTRUMENTS |                                |





COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: [No Variations]

|                                     |                                 |                   |                                |
|-------------------------------------|---------------------------------|-------------------|--------------------------------|
| PCB VIEWED FROM BOTTOM SIDE         | BOARD #: TIDA-00195             | REV: E1           | SUN REV: Not In VersionControl |
| LAYER NAME = ASSEMBLY BOTTOM        |                                 |                   |                                |
| PLOT NAME = Bottom Assembly Drawing | GENERATED : 23-03-2015 18:03:37 | TEXAS INSTRUMENTS |                                |

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